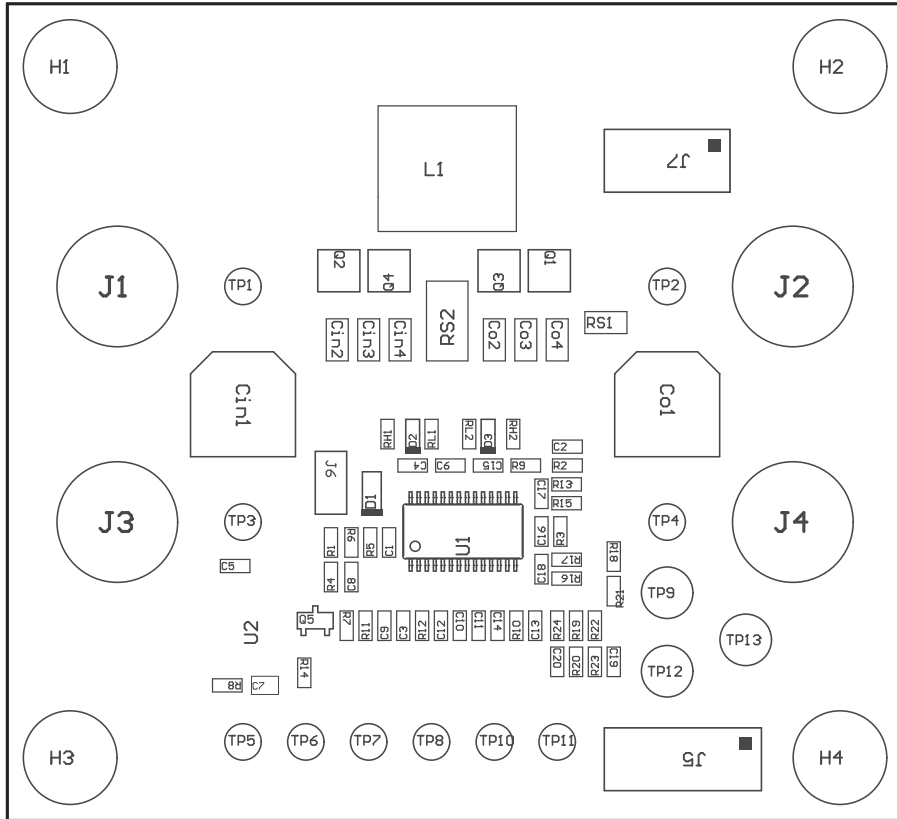


Z21 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.

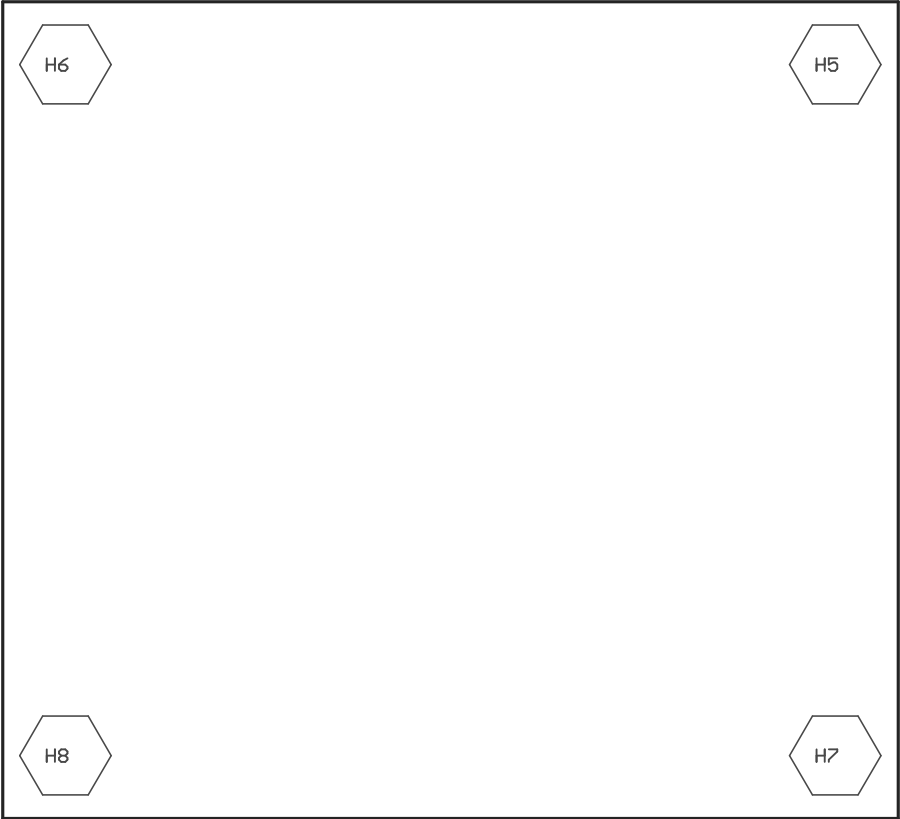
Z22 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

Z23 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: PMP10624	REV: A	SUN REV: Not In VersionControl
PLOT NAME = Top Assembly Drawing	GENERATED : 6/4/2015	4:32:29 PM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP10624	REV: A	SUN REV: Not In VersionControl
PLOT NAME = Bottom Assembly Drawing	GENERATED : 6/4/2015 4:32:30 PM	TEXAS INSTRUMENTS	

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